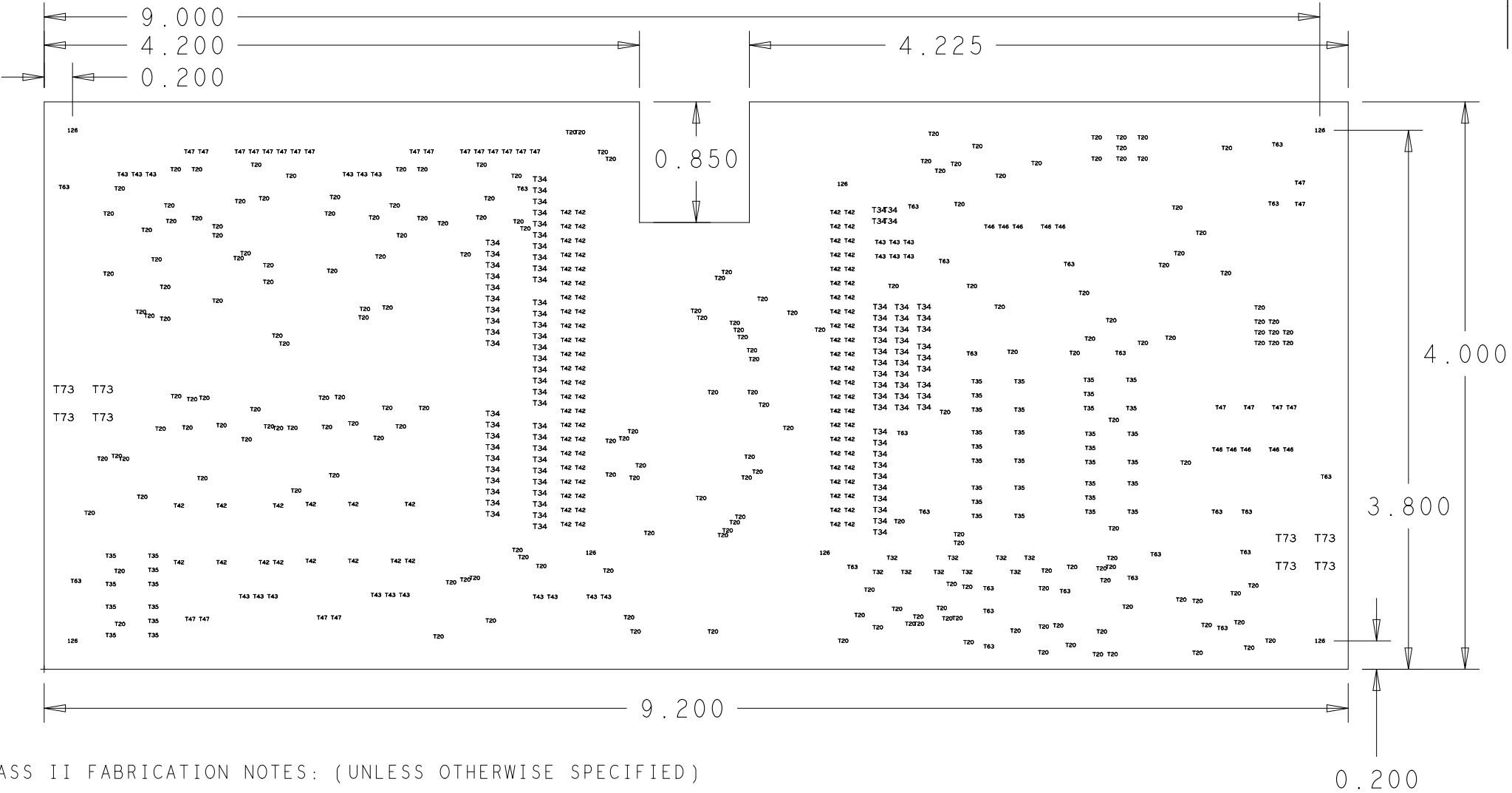


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED



	TOP COPPER
	IN1 COPPER
	IN2 COPPER
	BOTTOM COPPER

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
T20	20.0	PLATED	210
T32	32.0	PLATED	9
T34	34.0	PLATED	93
T35	35.0	PLATED	40
T42	42.0	PLATED	106
T43	43.0	PLATED	22
T46	46.0	PLATED	10
T47	47.0	PLATED	26
T63	63.0	PLATED	24
T73	73.0	PLATED	8
T26	126.0	PLATED	7

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:

a. FR4 PER IPC 4101B/24, /26, OR /28.

b. SIGNAL LAYERS TO BE 2 OZ. COPPER.

c. PLANE LAYERS TO BE 2 OZ. COPPER.

d. OVERALL THICKNESS TO BE 0.062" +/- 0.007"
4. LEGEND:

a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:

a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR GREEN, BOTH SIDES.
6. PLATING FINISH:

a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.

b. ~~IMMERSION SILVER PLATING.~~
7. PROCESS ALLOWANCES:

a. MAXIMUM BOW AND TWIST SHALL NOT EXCEED .007" PER INCH

b. HOLE DIMENSIONS APPLY AFTER PLATING.

c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.

d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003"

e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".

f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.

g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.

VISIBLE LAYERS

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	swFOCE Gateway Node Prototype			
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- 0.02" 3 PL DECIMALS +/- 0.005" ANGLES +/- 1 Degree FRACTIONS +			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE 7700 SANDHOLDT ROAD MOSS LANDING, CA			
			SIZE B	REVISION A	DWG NO 10020948	
	DESIGNED BY: CHAD KEYC		SCALE 1 - 1		SHEET 1 - 1	
	LAYOUT BY: JOSE ROSAL					